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A - [001] 011 04- 140 23& 231 236 316 359 431 445 477 609 623 627 678 720
722

AP - JP19800049686 19800415

CPY - MATU

DC - A85 L03

FS - CPI

IC - H01C7/00 ; H01C17/28 ; H01G1/01 ; H01G4/12 ; H01L21/28 ; H01L41/00

KS - 0231 1277 1996 2198 2200 2318 2440 2682 2729 2743 2857

MC - A12-E07B A12-E07V A12-W12D L03-A01A L03-B03

PA - (MATU) MATSUSHITA ELEC IND CO LTD

PN - JP56146218 A 19811113 DW198152 004pp

- JP63004331B B 19880128 DW198808 000pp

PR - JP19800049686 19800415

XIC - H01C-007/00 ; H01C-017/28 ; H01G-001/01 ; H01G-004/12 ; H01L-021/28 ;
H01L-041/00

AB - J56146218 Ag cpd. paste contg. 0.005-30 wt.% of Ag is coated on a
dielectric ceramic substrate except for edge portions. The Ag cpd.
paste on the substrate is heat-treated at 350-850 deg.C. to form Ag
layers. The Ag layers are electroless-plated with Cu to form metal
electrodes.

- Pref. the Ag cpd. is AgNO₃, Ag₂CO₃, Ag acetate or Ag cyanide.

Specifically, Ag cpd. paste is produced by mixing AgNO₃, phenol resin
as a binder and ethyl cellulose as a solvent. The Ag cpd. paste
contains 3 wt.% of Ag and has a viscosity of 30,000-60,000 CSP. The
paste is coated on both sides of a dielectric ceramic disk, dried at
80-100 deg.C. and fired at 600 deg.C to form Ag layers. The Ag layers
are plated with Cu.

- Cost of electrodes on electronic part e.g. a capacitor is reduced.

IW - PRODUCE ELECTRODE DIELECTRIC CERAMIC COATING CERAMIC SUBSTRATE SILVER
BASED PASTE HEAT TREAT ELECTROLESS PLATE COPPER

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NC - 001

OPD - 1980-04-15

ORD - 1981-11-13

PAW - (MATU) MATSUSHITA ELEC IND CO LTD

TI - Prodn. of electrode for dielectric ceramic - by coating ceramic
substrate with silver based paste, heat treating and electrolessly
plating with copper